

ICD-P620

SERVICE MANUAL

Ver. 1.1 2008.03



*US Model
Canadian Model
AEP Model
E Model*

SPECIFICATIONS

IC recorder section

Recording media

Built-in flash memory 512 MB, Monaural recording
A part of the memory capacity is used as a management area.

Recording time

HQ: 59 hours 45 minutes
SP: 159 hours 20 minutes
LP: 261 hours 45 minutes

Frequency range

HQ: 260 Hz - 6,800 Hz
SP/LP: 220 Hz - 3,400 Hz

General

Speaker

Approx. 2.8 cm (1 1/8 in.) dia.

Power output

250 mW

Input/Output

- Headphone jack (minijack) for 8 - 300 ohms ear receiver/headphones
- Microphone jack (minijack, monaural)
Plug in power
Minimum input level 0.6 mV
3 kilohms or lower impedance microphone
- USB connector

Power requirements

Two LR03 (size AAA) alkaline batteries: 3 V DC

Dimensions (w/h/d) (not incl. projecting parts and controls)

34.6 × 109.2 × 18.4 mm (1 3/8 × 4 3/8 × 3/4 in.)

Mass (incl. batteries)

67 g (2.4 oz)

Supplied accessories

Operating instructions (1)
LR03 (size AAA) alkaline batteries (2)
Headphone (1) (excluding the U.S.A., Canada and Europe)
Carrying pouch (1) (excluding the U.S.A., Canada and Europe)
USB connecting cable (1)
Application software (CD-ROM) (1)

Design and specifications are subject to change without notice.

IC RECORDER

9-887-971-02
2008C04-1
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Sony Corporation
Audio Business Group
Published by Sony Techno Create Corporation

SONY®

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Notes on chip component replacement

- Never reuse a disconnected chip component.
- Notice that the minus side of a tantalum capacitor may be damaged by heat.

Flexible Circuit Board Repairing

- Keep the temperature of soldering iron around 270 °C during repairing.
- Do not touch the soldering iron on the same conductor of the circuit board (within 3 times).
- Be careful not to apply force on the conductor when soldering or unsoldering.

UNLEADED SOLDER

Boards requiring use of unleaded solder are printed with the lead-free mark (LF) indicating the solder contains no lead.

(Caution: Some printed circuit boards may not come printed with the lead free mark due to their particular size)

 : LEAD FREE MARK

Unleaded solder has the following characteristics.

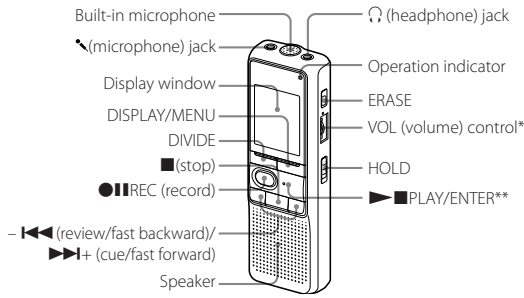
- Unleaded solder melts at a temperature about 40 °C higher than ordinary solder.
Ordinary soldering irons can be used but the iron tip has to be applied to the solder joint for a slightly longer time.
Soldering irons using a temperature regulator should be set to about 350 °C.
Caution: The printed pattern (copper foil) may peel away if the heated tip is applied for too long, so be careful!
- Strong viscosity
Unleaded solder is more viscous (sticky, less prone to flow) than ordinary solder so use caution not to let solder bridges occur such as on IC pins, etc.
- Usable with ordinary solder
It is best to use only unleaded solder but unleaded solder may also be added to ordinary solder.

SECTION 1 GENERAL

This section is extracted from instruction manual.

Index to Parts and Controls

Main unit

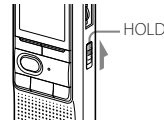


* There is a tactile dot beside the control to show the direction to turn up the volume.
 ** The button has a tactile dot.

Preventing Accidental Operation

— HOLD function

Slide the HOLD switch to ON. "HOLD" will flash three times, indicating that all the functions of the buttons are locked. When the HOLD function is activated during stop, all the display will be turned off after "HOLD" flashes.



To cancel the HOLD function

Slide the HOLD switch to OFF.

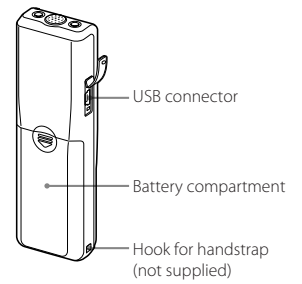
■ Note

When the HOLD function is activated during recording, cancel the HOLD function first to stop recording.

💡 Tip

Even if the HOLD function is activated, you can stop the alarm playback. To stop the alarm or playback, press ■ (stop).

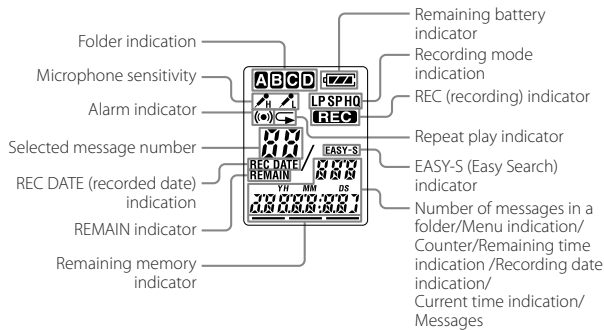
Rear



6^a

7^a

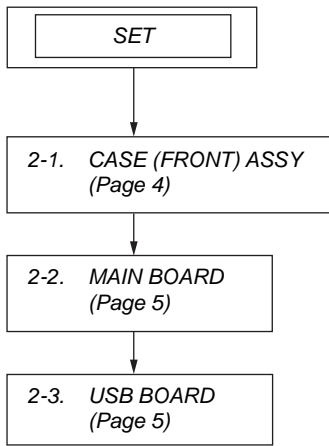
Display window



8^a

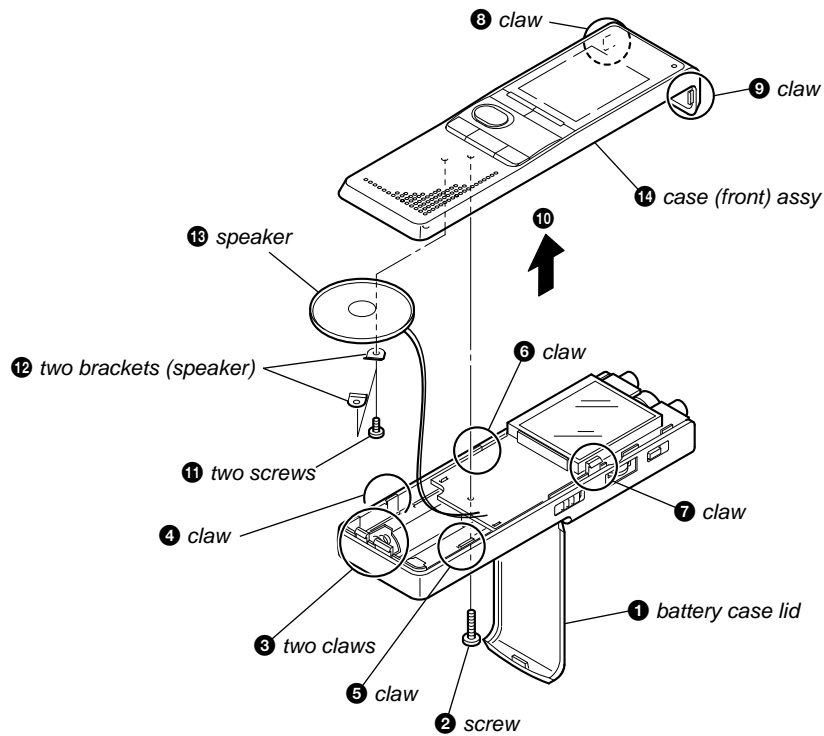
SECTION 2 DISASSEMBLY

- This set can be disassembled in the order shown below.

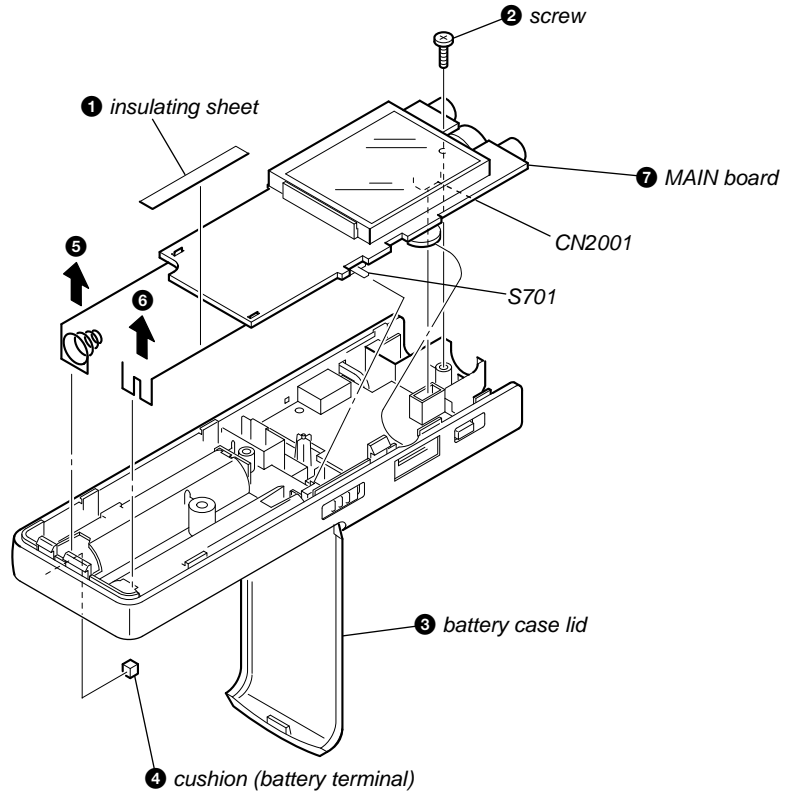


Note: Follow the disassembly procedure in the numerical order given.

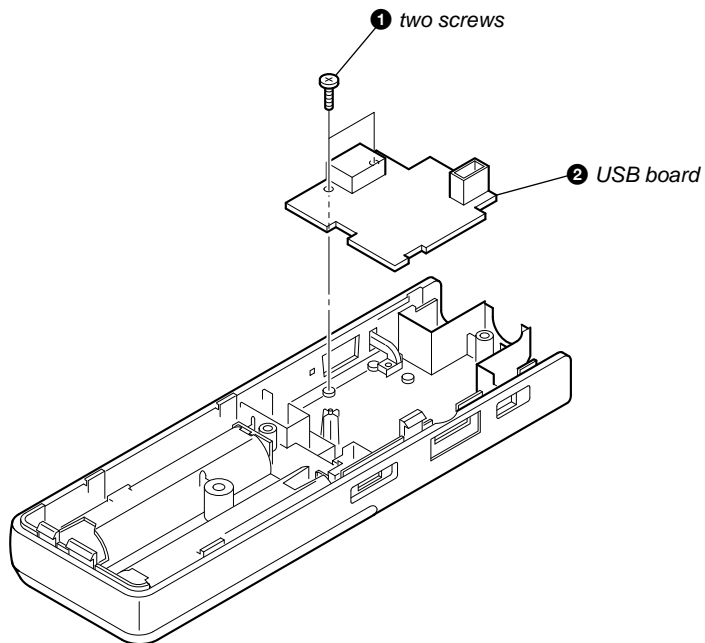
2-1. CASE (FRONT) ASSY



2-2. MAIN BOARD



2-3. USB BOARD



SECTION 3 TEST MODE

1. Outline of the TEST MODE

The TEST MODE is designed to help verify the set when servicing it.

The TEST MODE is only menu driven to select modes for servicing.

2. Entering and Canceling the TEST MODE

With the power on, turn on the [HOLD] switch while pressing the [■] button and the [DISPLAY/MENU] button at the same time.

3. Canceling the TEST MODE

The TEST MODE can be cancelled by turning off the power (unplugging the dry battery).

4. Menu Key Designation

The menu has the five modes described below. The following keys are assigned on the initial screen (version display).

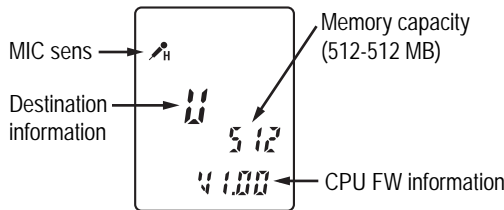
5. Key Assignment

From within TEST MODE, the intended menu can be entered by using the appropriate one key of the following key.

LCD Test (All On↔All Off)	DISPLAY/MENU
BEEP Test (1.3 kHz)	ERASE
HQ-DSP LOOP	● REC
SP-DSP LOOP	- <<<
LP-DSP LOOP	>>> +
USB Test	▶■PLAY/ENTER
REST MENU Test	DIVIDE
Initial Display from each mode	■

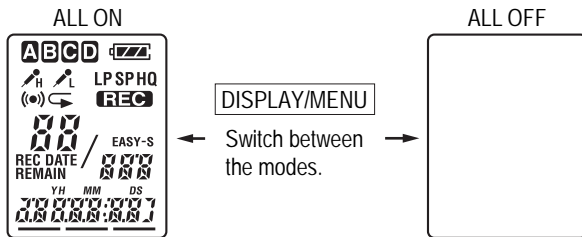
5-1. Initial Display in TEST MODE

LCD indications (destination information, memory capacity, CPU FW information and MIC sens) when TEST MODE is entered:



5-2. LCD Test

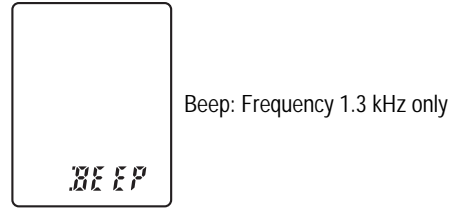
To enter the LCD Test, press the [DISPLAY/MENU] button. The LCD Test has two modes: All On and All Off First all the indicators are on. All the indicators are off when the button is pressed again.



Press the [■] button to return to the initial display (destination information, memory capacity, CPU FW information and MIC sens).

5-3. BEEP Test

To enter the BEEP Test, press the [ERASE] button.



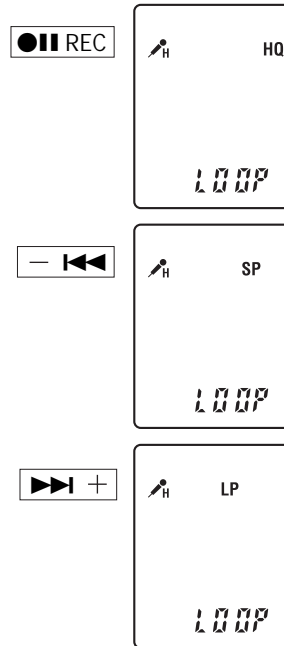
Press the [■] button to return to the initial screen (memory and CPU version).

5-4. DSP LOOP

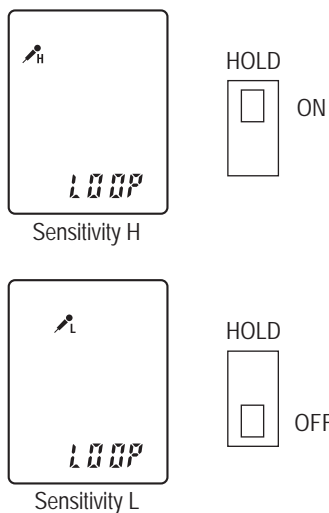
The DSP LOOP modes can be entered selectively by pressing the appropriate one of the following three keys.

Within the LOOP test menu, "LOOP" is displayed. The sensitivity character H or L is displayed depending on the position into which the [HOLD] switch is placed.

The sensitivity H is displayed when [HOLD] switch is in the ON position. The sensitivity L is displayed when [HOLD] switch is in the OFF position.



To change the DSP LOOP test mode, press the [■] button, then select the [●||REC] button, [- <<<] button, or [>>> +] button. In a DSP Test mode, to select another DSP Test mode and to select the other sensitivity, the [■] button also has to be pressed.

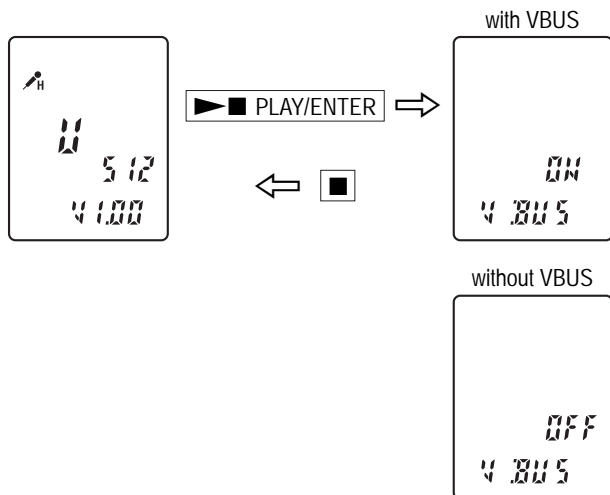


To change the sensitivity again, press the [■] button and change the [HOLD] switch.
 In a DSP Test mode, changing the mode and changing the sensitivity require the [■] button be pressed.

5-5. USB Test

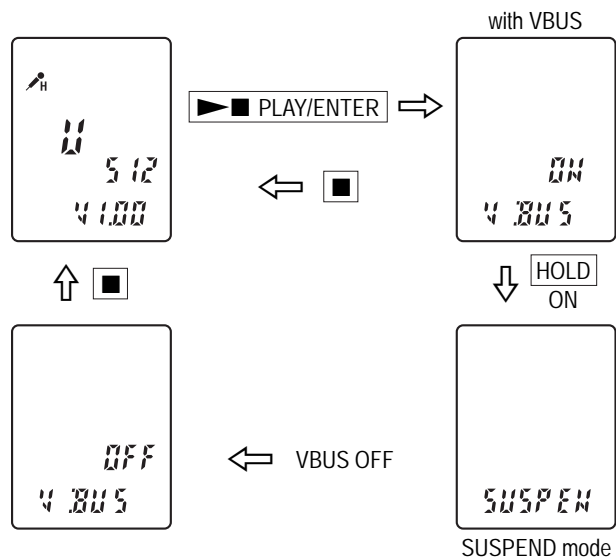
In this test, the ON/OFF status of VBUS is displayed and the SUSPEND test is performed.
 The [▶■]PLAY/ENTER button is pressed to display the status of VBUS by “On” or “OFF” indication.
 With the VBUS ON, the [HOLD] switch is operated (ON) to perform the SUSPEND test.

• VBUS Test



• SUSPEND Test

With the VBUS ON, turn the [HOLD] switch ON to enter the SUSPEND mode.
 When this mode is cancelled, the VBUS is turned OFF.

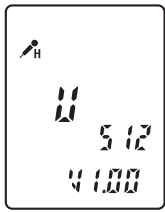


5-6. RESET MENU

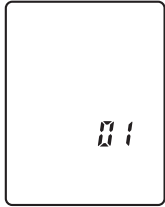
To enter the RESET MENU test, press the [DIVIDE] button.
 When all of the buttons or controls located on the set are operated, the system shows “Ok” if all of them are normally operated.
 An operation of a switch is indicated by the number for verification in order to make a simple indication.

Note 1: When 10 different operations of the switches are normally made in any order (regardless of the order that pushbuttons are pressed and the slide switch is set to ON and OFF), the system shows “Ok”.

Note 2: Clear memory when “ACCESS” is blinking on the display. (Do this before “Ok” is shown.) To exit from this menu, the power has to be turned off (battery to be removed).



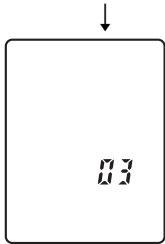
Press **DIVIDE** button.



Indication after **DIVIDE** button is pressed.

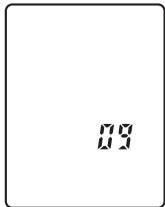


Indication after **DISPLAY/MENU** button is pressed.

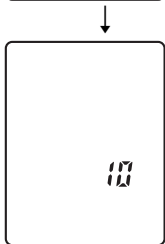


Indication after **REC** button is pressed.

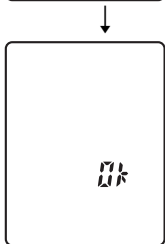
⋮



Indication after **HOLD** is set to OFF.



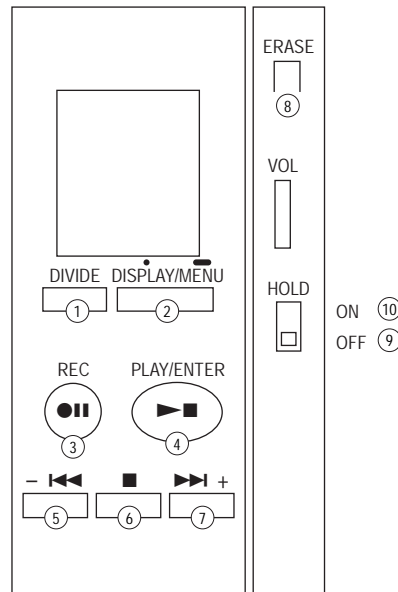
Indication after **HOLD** is set to ON.
 → If any key is not pressed, the system waits for the key to be pressed.



Clear memory when "ACCESS" is blinking on the display. The system shows "Ok".

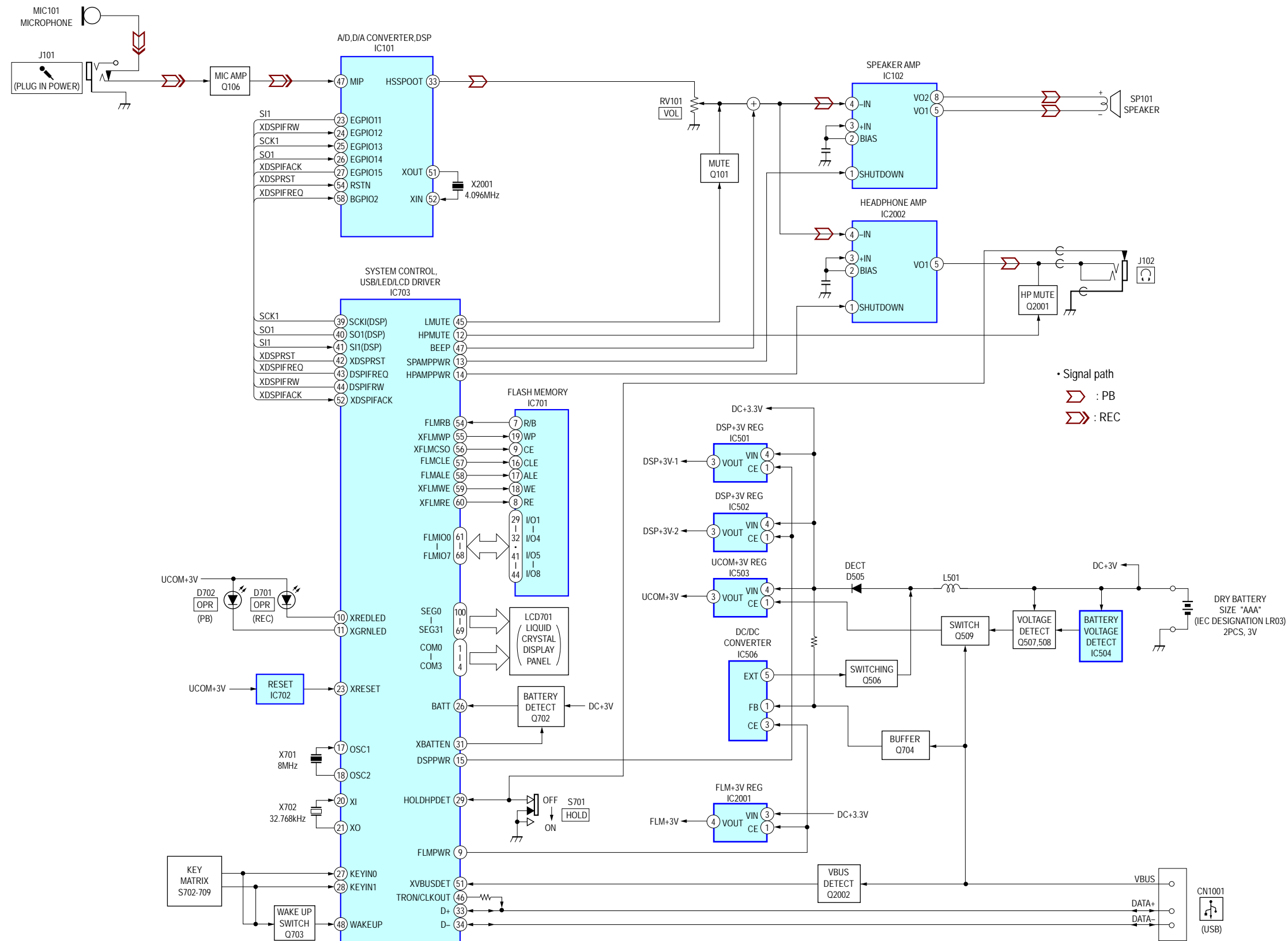
• Switches and corresponding LCD indications

Switch	Indication
DIVIDE	1
DISPLAY/MENU	2
● REC	3
▶■PLAY/ENTER	4
- ◀◀	5
■	6
▶▶ +	7
ERASE	8
HOLD-OFF	9
HOLD-ON	10



SECTION 4 DIAGRAMS

4-1. BLOCK DIAGRAM



THIS NOTE IS COMMON FOR PRINTED WIRING BOARDS AND SCHEMATIC DIAGRAMS.
 (In addition to this, the necessary note is printed in each block.)

For Printed Wiring Boards.

Note:

- : Parts extracted from the component side.
- : parts extracted from the conductor side.
- △ : internal component.
- : Pattern from the side which enables seeing.

Caution:

Pattern face side: Parts on the pattern face side seen from the pattern face are indicated.
 (SIDE B)
 Parts face side: Parts on the parts face side seen from the parts face are indicated.
 (SIDE A)

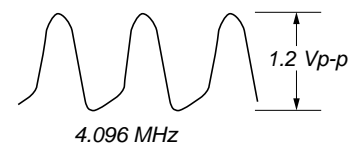
For Schematic Diagrams.

Note:

- All capacitors are in μF unless otherwise noted. (p: pF) 50 WV or less are not indicated except for electrolytics and tantalums.
- All resistors are in Ω and $1/4\text{ W}$ or less unless otherwise specified.
- △ : internal component.
- : panel designation.
- : B+ Line.
- Power voltage is dc 3 V and fed with regulated dc power supply from battery terminal.
- Voltages and waveforms are dc with respect to ground under no-signal (detuned) conditions.
- Main (1/2), (2/2) sections –
 no mark : PB
 () : REC
- Voltages are taken with a VOM (Input impedance 10 M Ω). Voltage variations may be noted due to normal production tolerances.
- Waveforms are taken with a oscilloscope. Voltage variations may be noted due to normal production tolerances.
- Circled numbers refer to waveforms.
- Signal path.
- Σ : PB
- Σ : REC

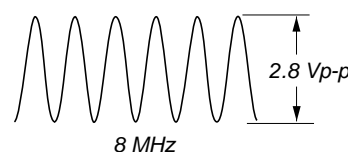
Waveforms
 – MAIN Board –

① IC101 (XOUT)



0.5 V/DIV, 0.1 $\mu\text{sec}/\text{DIV}$

② IC703 (OSC2)



0.5 V/DIV, 0.1 $\mu\text{sec}/\text{DIV}$

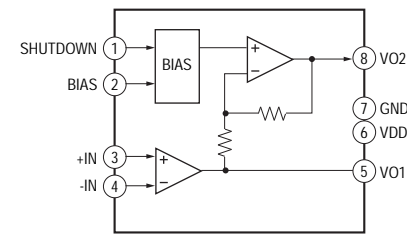
③ IC703 (XO)



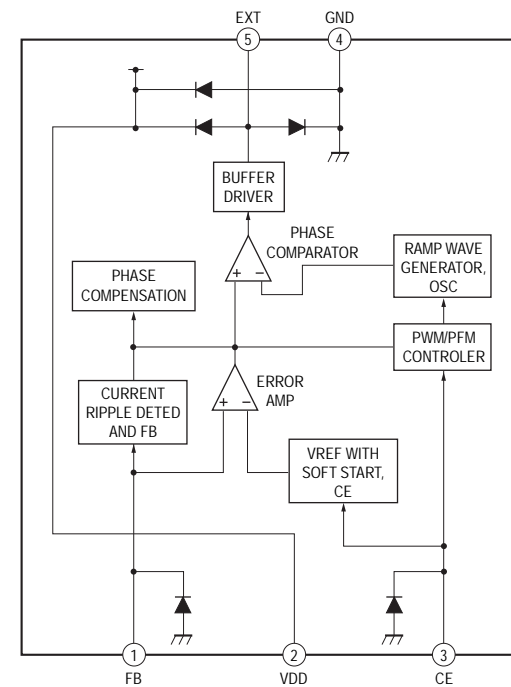
0.5 V/DIV, 20 $\mu\text{sec}/\text{DIV}$

IC Block Diagrams

IC102 MM3111AWLE (MAIN Board (1/2))
 IC2002 MM3111AWLE (MAIN Board (1/2))



IC506 XC9105D091MR (MAIN Board (1/2))

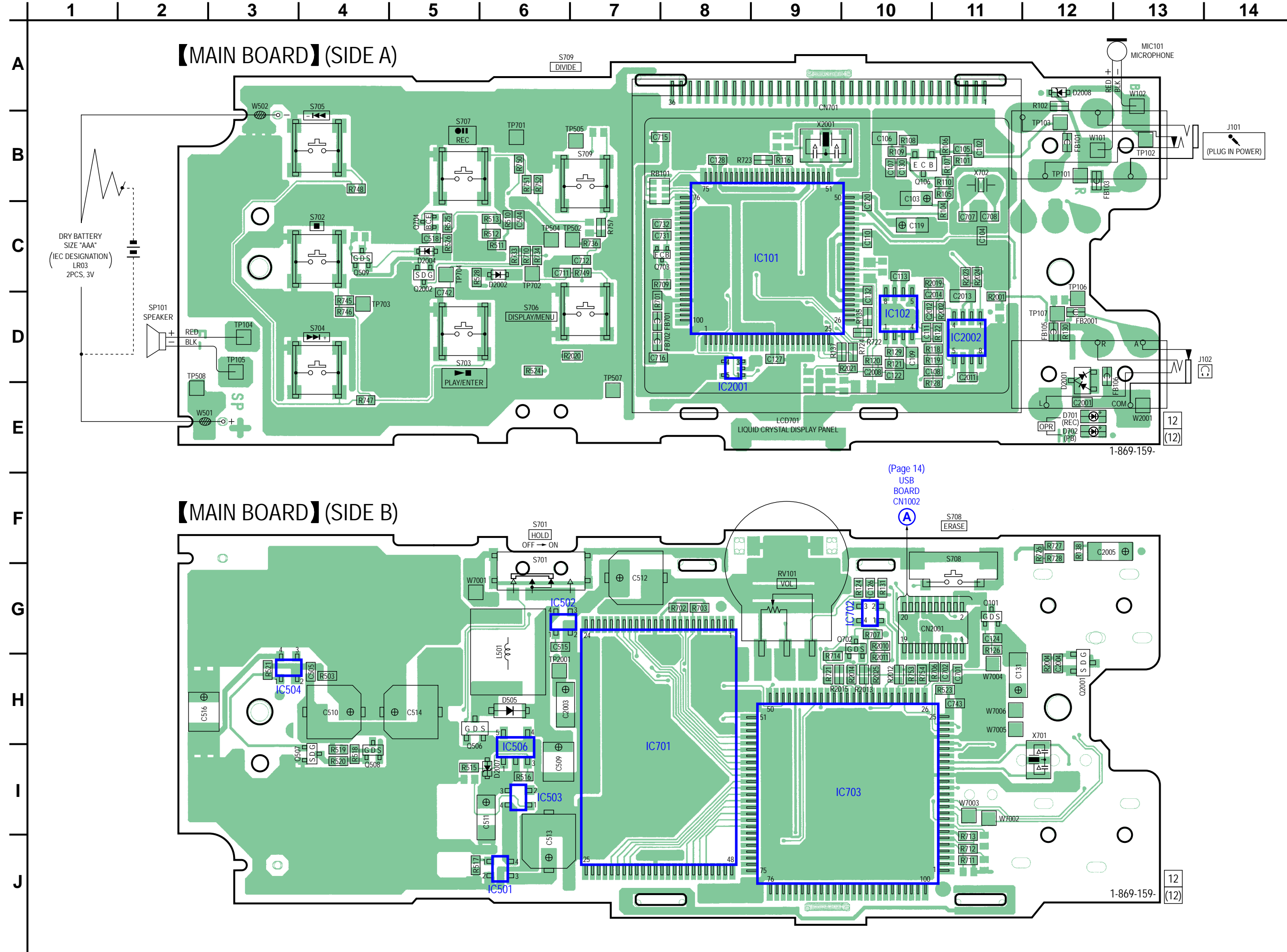


Semiconductor Location (MAIN Section)

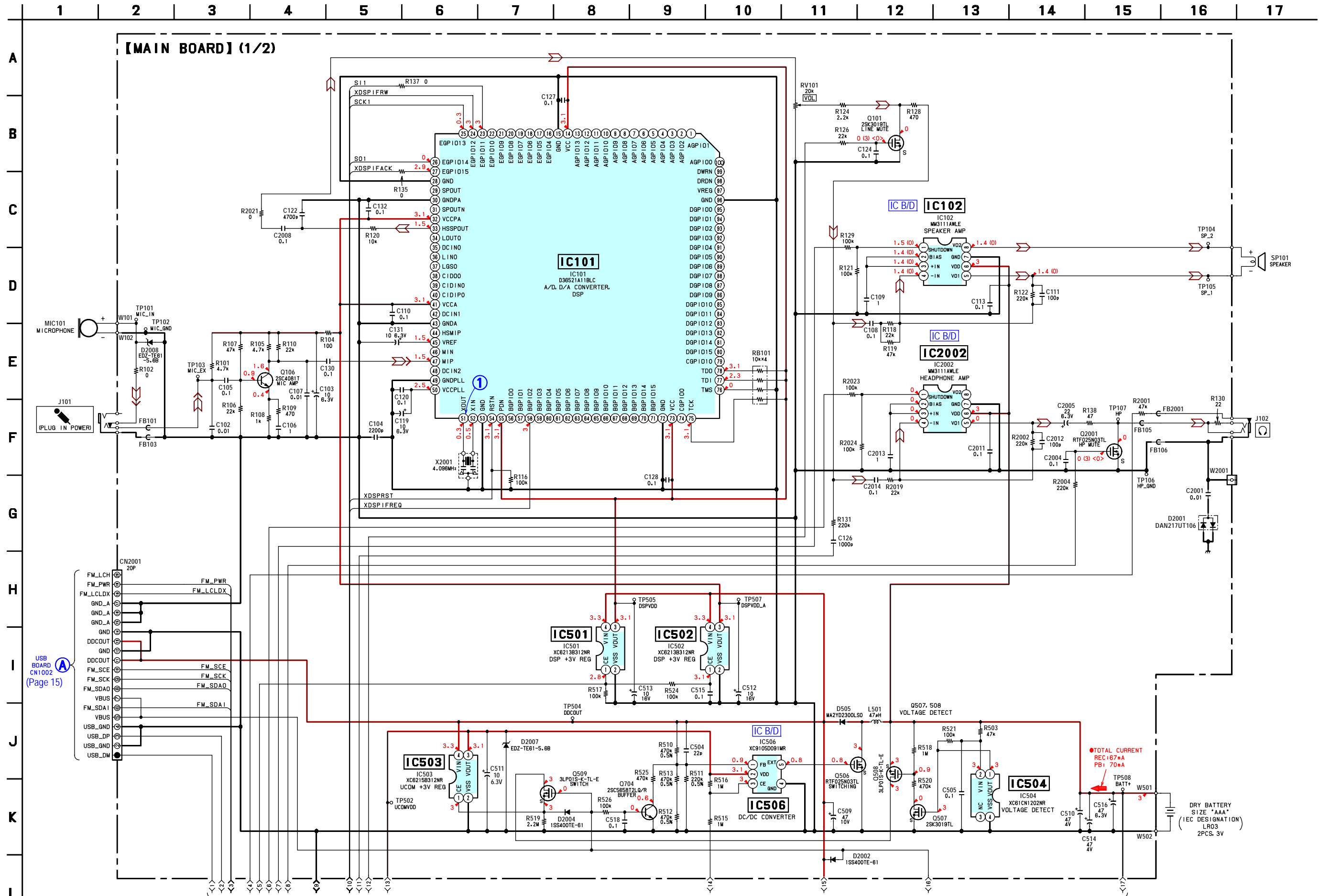
Ref. No.	Location
(D505)	H-6
D701	E-12
D702	E-12
D2001	E-12
D2002	C-6
D2004	C-5
(D2007)	I-6
D2008	A-12
IC101	C-9
IC102	D-10
(IC501)	J-6
(IC502)	G-6
(IC503)	I-6
(IC504)	H-3
(IC506)	I-6
(IC701)	I-8
(IC702)	G-10
(IC703)	I-10
IC2001	D-8
IC2002	D-11
(Q101)	G-11
Q106	B-10
(Q506)	H-5
(Q507)	I-4
(Q508)	I-4
Q509	C-4
(Q702)	G-10
Q703	C-8
Q704	C-5
(Q2001)	H-12
Q2002	C-5

() : SIDE B

4-2. PRINTED WIRING BOARD – MAIN Section – • See page 10 for Semiconductor Location. • : Uses unleaded solder.

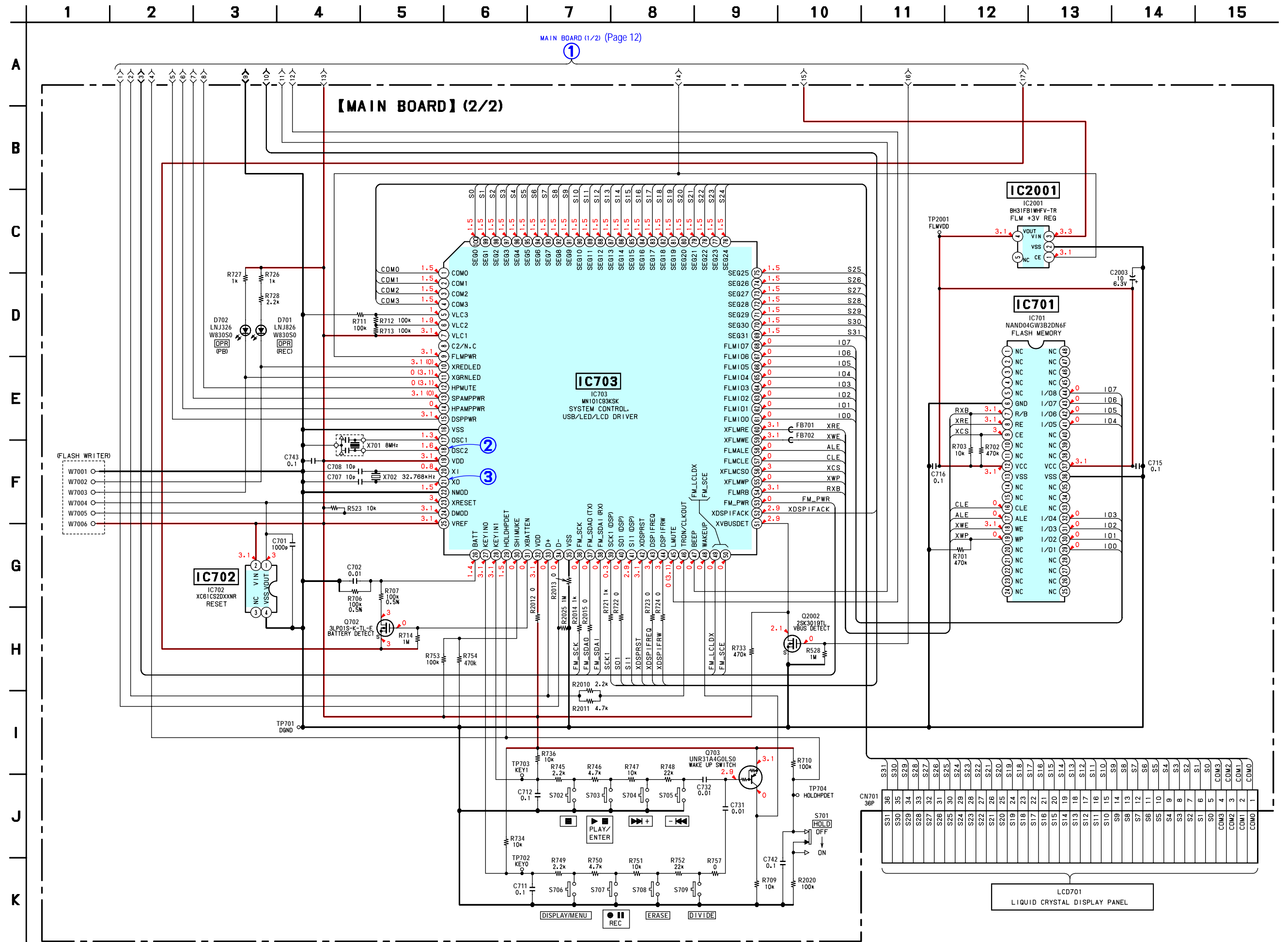


4-3. SCHEMATIC DIAGRAM – MAIN Section (1/2) – • See page 10 for waveform. • See page 10 for IC Block Diagrams.

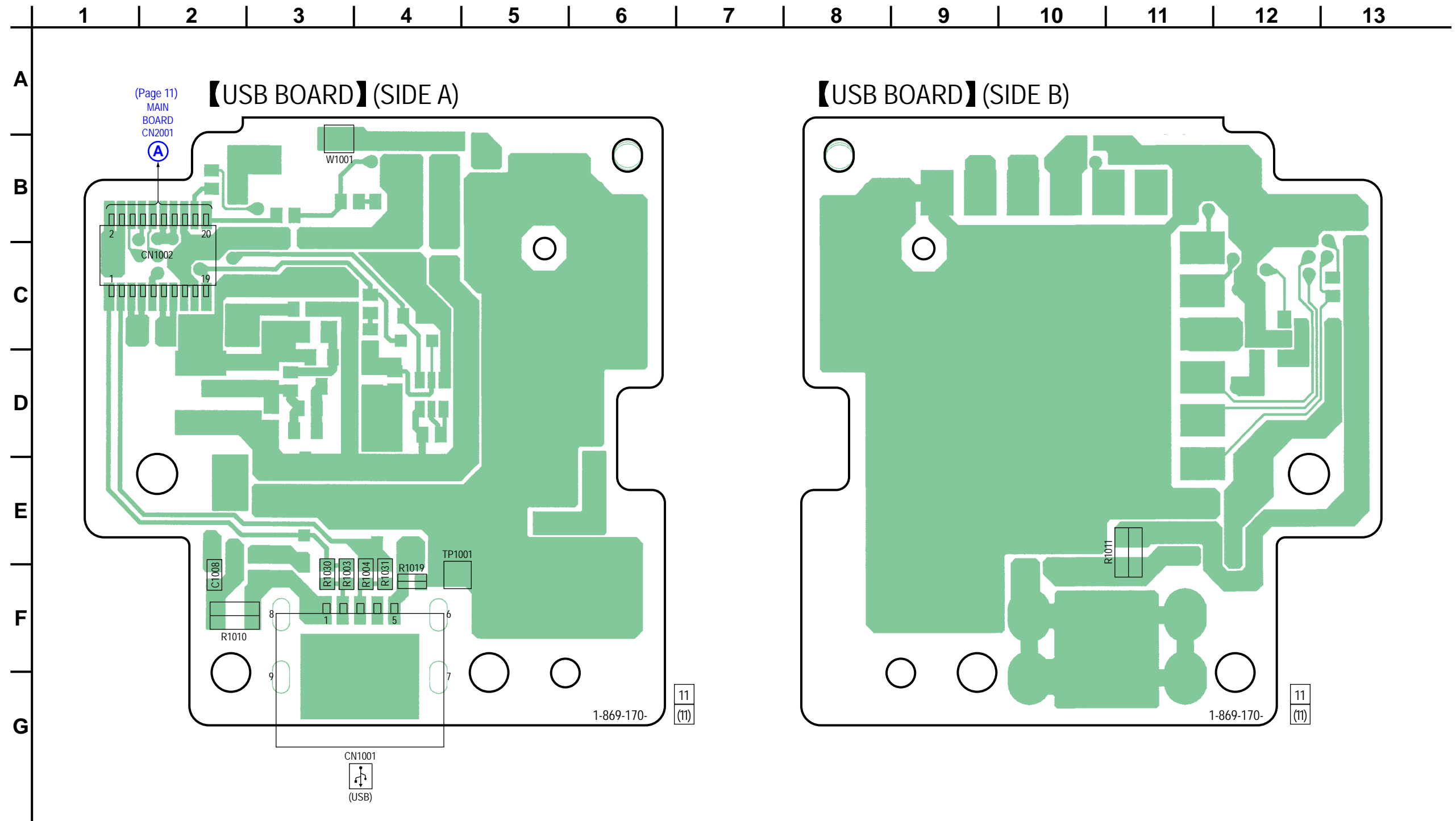


1 MAIN BOARD (2/2) (Page 13)

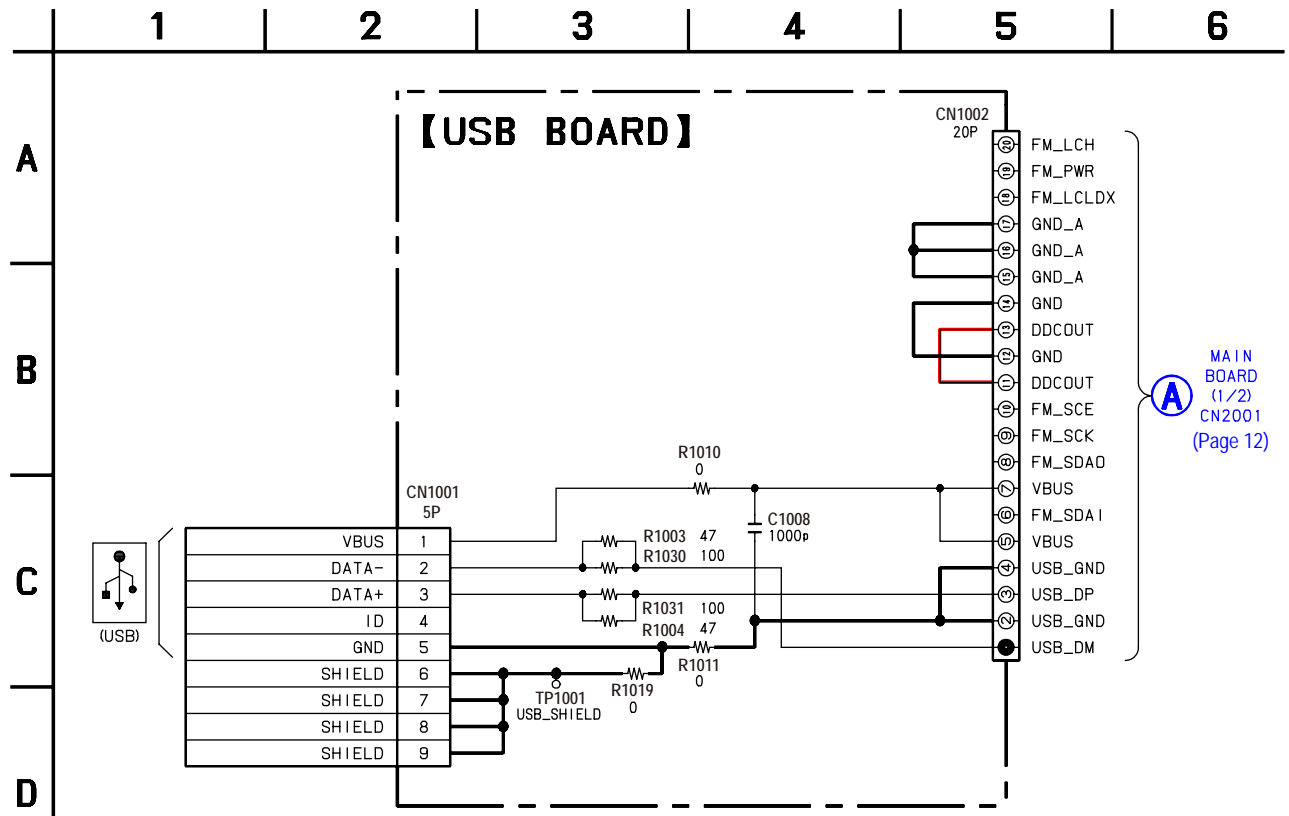
4-4. SCHEMATIC DIAGRAM – MAIN Section (2/2) – • See page 10 for waveforms. • See page 16 for IC Pin Function Description of IC703.



4-5. PRINTED WIRING BOARD – USB Section – • **LF** : Uses unleaded solder.



4-6. SCHEMATIC DIAGRAM – USB Section –



• IC Pin Function Description

IC703 MN101C93KSK (SYSTEM CONTROL, USB/LED/LCD DRIVER) (MAIN BOARD (2/2))

Pin No.	Pin Name	I/O	Description
1 to 4	COM0 to 3	O	LCD common 0 to 3 signal output
5 to 7	VLC3 to 1	I	LCD VLC 3 to 1 signal input
8	C2/N.C	I	Not used (Open)
9	FLMPWR	O	Flash memory power ON signal output (H: ON, L: OFF)
10	XREDLED	O	Red LED ON/OFF signal output (Open drain)
11	XGRNLED	O	Green LED ON/OFF signal output (Open drain)
12	HPMUTE	O	Headphone muting signal output (H: Muting)
13	SPAMPPWR	O	Speaker power amplifier power ON signal output (H: ON, L: OFF)
14	HPAMPPWR	O	Headphone power amplifier power ON signal output (H: ON, L: OFF)
15	DSPPWR	O	DSP power control signal output (H: ON, L: OFF)
16	VSS	—	Ground
17	OSC1	I	Main clock input (8 MHz)
18	OSC2	O	Main clock output (8 MHz)
19	VDD	—	Power supply (+3.1 V)
20	XI	I	Sub clock input (32.768 kHz)
21	XO	O	Sub clock output (32.768 kHz)
22	NMOD	I	Not used (Connected to GND)
23	XRESET	I	CPU reset signal input
24	DMOD	I	Not used (Pull up)
25	VREF	I	Reference voltage input for A/D converter. (+3.1 V)
26	BATT	I	Battery level A/D input
27	KEYIN0	I	Key 0 A/D input
28	KEYIN1	I	Key 1 A/D input
29	HOLDHPDET	I	HOLD switch/headphone detection signal input
30	SHIMUKE	I	Destination setting pin
31	XBATTEN	O	Battery level sense enable signal output (L: Enable)
32	VDD	—	Power supply (+3.1 V)
33	D+	I/O	USB D+ signal input/output
34	D-	I/O	USB D- signal input/output
35	VSS	—	Ground
36	FM_SCK	O	FM tuner serial clock output (Not used in this set.)
37	FM_SDAO(TX)	O	FM tuner serial data output (Not used in this set.)
38	FM_SDAI(RX)	I	FM tuner serial data input (Not used in this set.)
39	SCK1(DSP)	O	DSP I/F serial clock output
40	SO1(DSP)	O	DSP I/F serial data output
41	SI1(DSP)	I	DSP I/F serial data input
42	XDSPRST	O	DSP reset signal output (L: Reset)
43	DSPIFREQ	O	DSP I/F request signal output
44	DSPIFRW	O	DSP I/F read/write signal output
45	LMUTE	O	Audio line muting signal output
46	TRON/CLKOUT	O	USB TRON signal output
47	BEEP	O	Beep signal output
48	WAKEUP	I	Wakeup interruption signal input
49	FM_LCLDX	O	FM Local/DX ON signal output (Not used in this set.)
50	FM_SCE	O	FM serial chip select signal output (Not used in this set.)
51	XVBUSDET	I	VBUS detection signal input (L: VBUS ON)
52	XDSPIFACK	I	DSP acknowledge interruption signal input
53	FM_PWR	O	FM tuner power ON signal output (Not used in this set.)

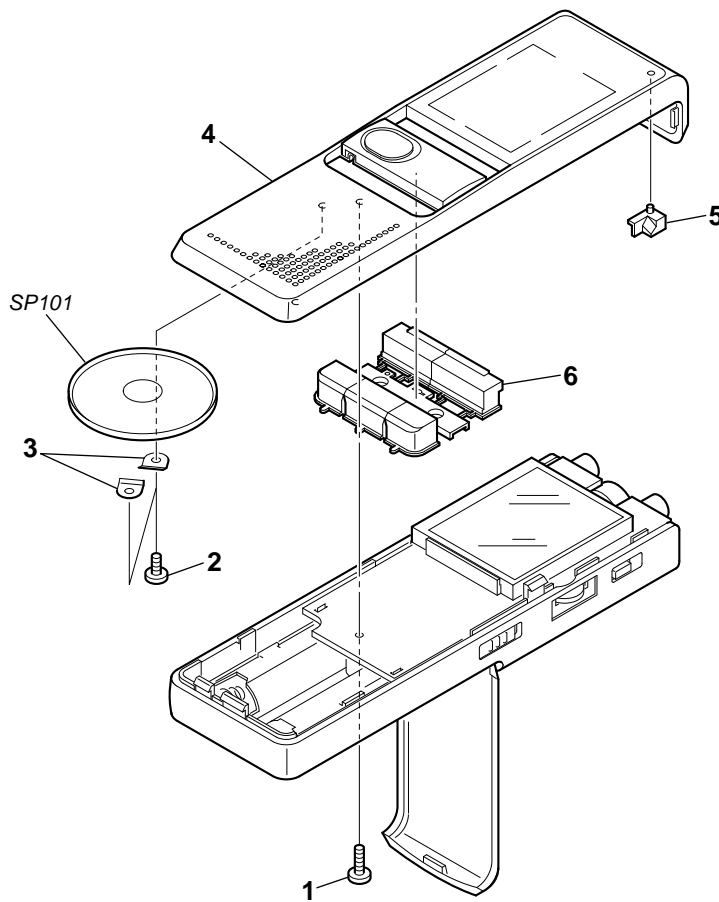
Pin No.	Pin Name	I/O	Description
54	FLMRB	I	Flash memory ready/busy signal input
55	XFLMWP	O	Flash memory write protect signal output
56	XFLMCS0	O	Flash memory chip select signal output
57	FLMCLE	O	Flash memory command latch enable signal output
58	FLMALE	O	Flash memory address latch enable signal output
59	XFLMWE	O	Flash memory write enable clock signal output
60	XFLMRE	O	Flash memory read enable clock signal output
61 to 68	FLMIO0 to 7	I/O	Flash memory address/data bit0 to 7 signal input/output
69 to 100	SEG31 to 0	O	LCD segment 31 to 0 signal output

SECTION 5 EXPLODED VIEWS

Note:

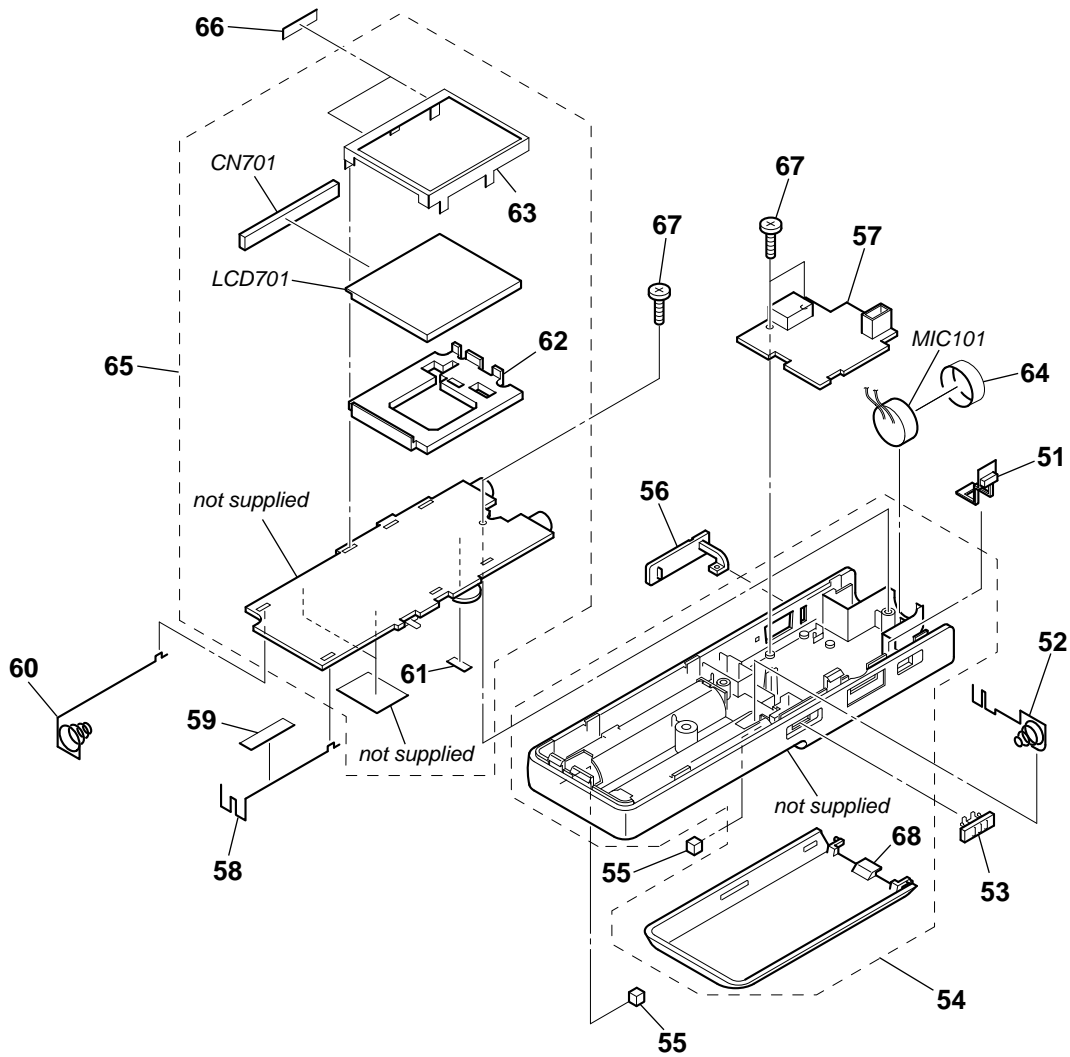
- -XX and -X mean standardized parts, so they may have some difference from the original one.
- Items marked “*” are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.
- The mechanical parts with no reference number in the exploded views are not supplied.

5-1. CASE (FRONT) SECTION



Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
1	3-254-083-01	SCREW		5	3-292-056-01	LENS (LED)	
2	3-254-003-01	SCREW		6	3-292-053-11	BUTTON (FRONT)	
3	2-634-641-01	BRACKET (SPEAKER)		SP101	1-826-927-11	SPEAKER (2.8cm)	
4	X-2188-741-1	CASE (FRONT) SUB ASSY (P)					

5-2. CASE (REAR) SECTION



Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
51	2-633-874-31	BUTTON (SIDE)		62	2-661-298-01	SPACER (LCD-P)	
52	2-633-876-01	TERMINAL (+,-), BATTERY		63	2-633-872-01	HOLDER (LCD)	
53	2-633-870-31	KNOB (HOLD)		64	2-590-076-01	CUSHION (MIC)	
54	X-2188-740-1	CASE (REAR) SUB ASSY (P)		65	A-1486-574-A	MAIN BOARD, COMPLETE	
55	2-177-065-01	CUSHION (BATTERY TERMINAL)		66	2-653-251-01	SHEET	
56	2-634-640-11	LID (CONNECTOR)		67	3-254-014-01	SCREW	
57	A-1486-576-A	USB BOARD, COMPLETE		68	2-633-869-51	LID, BATTERY CASE	
58	2-633-877-01	TERMINAL (+), BATTERY		CN701	1-780-296-21	CONDUCTIVE BOARD, CONNECTION	
59	2-590-020-01	SHEET, INSULATING		LCD701	1-802-628-11	DISPLAY PANEL, LIQUID CRYSTAL	
60	2-633-878-02	TERMINAL (-), BATTERY		MIC101	1-542-758-11	MICROPHONE, ELECTRET CONDENSER (MIC)	
61	3-251-410-02	SHEET, INSULATING					

SECTION 6 ELECTRICAL PARTS LIST

MAIN

Note:

- Due to standardization, replacements in the parts list may be different from the parts specified in the diagrams or the components used on the set.
- -XX and -X mean standardized parts, so they may have some difference from the original one.
- Items marked "*" are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.
- CAPACITORS
uF: μF
- COILS
uH: μH

- RESISTORS
All resistors are in ohms.
METAL: Metal-film resistor.
METAL OXIDE: Metal oxide-film resistor.
F: nonflammable
- SEMICONDUCTORS
In each case, u: μ, for example:
uA. . . : μA. . . , uPA. . . , μPA. . . ,
uPB. . . : μPB. . . , uPC. . . , μPC. . . ,
uPD. . . : μPD. . .
- Abbreviation
CND : Canadian model
KR : Korea model

When indicating parts by reference number, please include the board name.

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
	A-1486-574-A	MAIN BOARD, COMPLETE *****		C715	1-125-777-11	CERAMIC CHIP 0.1uF 10%	10V
				C716	1-125-777-11	CERAMIC CHIP 0.1uF 10%	10V
	2-633-872-01	HOLDER (LCD)		C731	1-164-943-81	CERAMIC CHIP 0.01uF 10%	16V
	2-661-298-01	SPACER (LCD-P)		C732	1-164-943-81	CERAMIC CHIP 0.01uF 10%	16V
	3-251-410-02	SHEET, INSULATING		C742	1-125-777-11	CERAMIC CHIP 0.1uF 10%	10V
		< CAPACITOR >		C743	1-125-777-11	CERAMIC CHIP 0.1uF 10%	10V
C102	1-164-943-81	CERAMIC CHIP 0.01uF	10% 16V	C2001	1-164-943-81	CERAMIC CHIP 0.01uF 10%	16V
C103	1-117-919-11	TANTAL. CHIP 10uF	20% 6.3V	C2003	1-135-259-11	TANTAL. CHIP 10uF 20%	6.3V
C104	1-164-939-11	CERAMIC CHIP 0.0022uF	10% 50V	C2004	1-125-777-11	CERAMIC CHIP 0.1uF 10%	10V
C105	1-125-777-11	CERAMIC CHIP 0.1uF	10% 10V	C2005	1-119-750-11	TANTAL. CHIP 22uF 20%	6.3V
C106	1-125-837-11	CERAMIC CHIP 1uF	10% 6.3V	C2008	1-125-777-11	CERAMIC CHIP 0.1uF 10%	10V
C107	1-164-943-81	CERAMIC CHIP 0.01uF	10% 16V	C2011	1-125-777-11	CERAMIC CHIP 0.1uF 10%	10V
C108	1-125-777-11	CERAMIC CHIP 0.1uF	10% 10V	C2012	1-164-931-11	CERAMIC CHIP 100PF 10%	50V
C109	1-125-837-11	CERAMIC CHIP 1uF	10% 6.3V	C2013	1-125-837-11	CERAMIC CHIP 1uF 10%	6.3V
C110	1-125-777-11	CERAMIC CHIP 0.1uF	10% 10V	C2014	1-125-777-11	CERAMIC CHIP 0.1uF 10%	10V
C111	1-164-931-11	CERAMIC CHIP 100PF	10% 50V			< CONNECTOR >	
C113	1-125-777-11	CERAMIC CHIP 0.1uF	10% 10V	CN701	1-780-296-21	CONDUCTIVE BOARD, CONNECTION	
C119	1-117-919-11	TANTAL. CHIP 10uF	20% 6.3V	CN2001	1-819-211-21	CONNECTOR, BOARD TO BOARD 20P	
C120	1-125-777-11	CERAMIC CHIP 0.1uF	10% 10V			< DIODE >	
C122	1-164-941-11	CERAMIC CHIP 0.0047uF	10% 16V	D505	8-719-085-43	DIODE MA2YD2300LS0	
C124	1-125-777-11	CERAMIC CHIP 0.1uF	10% 10V	* D701	6-502-310-01	LED LNJ826W830S0	
C126	1-164-937-11	CERAMIC CHIP 0.001uF	10% 50V	D702	6-502-309-01	LED LNJ326W830S0	
C127	1-125-777-11	CERAMIC CHIP 0.1uF	10% 10V	* D2001	6-501-855-01	DIODE DAN217UT106	
C128	1-125-777-11	CERAMIC CHIP 0.1uF	10% 10V	D2002	8-719-069-28	DIODE 1SS400TE-61	
C130	1-125-777-11	CERAMIC CHIP 0.1uF	10% 10V	D2004	8-719-069-28	DIODE 1SS400TE-61	
C131	1-135-259-11	TANTAL. CHIP 10uF	20% 6.3V	D2007	8-719-074-67	DIODE EDZ-TE61-5.6B	
C132	1-125-777-11	CERAMIC CHIP 0.1uF	10% 10V	D2008	8-719-074-67	DIODE EDZ-TE61-5.6B	
C504	1-164-858-11	CERAMIC CHIP 22PF	5% 50V			< FERRITE BEAD >	
C505	1-125-777-11	CERAMIC CHIP 0.1uF	10% 10V	FB101	1-400-693-21	INDUCTOR, FERRITE BEAD (1005)	
C509	1-137-934-11	TANTAL. CHIP 47uF	20% 10V	FB103	1-400-693-21	INDUCTOR, FERRITE BEAD (1005)	
C510	1-126-208-21	ELECT CHIP 47uF	20% 4V	FB105	1-400-693-21	INDUCTOR, FERRITE BEAD (1005)	
C511	1-135-259-11	TANTAL. CHIP 10uF	20% 6.3V	FB106	1-400-693-21	INDUCTOR, FERRITE BEAD (1005)	
C512	1-124-779-00	ELECT CHIP 10uF	20% 16V	FB701	1-469-581-21	INDUCTOR, FERRITE BEAD (1005)	
C513	1-124-779-00	ELECT CHIP 10uF	20% 16V				
C514	1-126-208-21	ELECT CHIP 47uF	20% 4V	FB702	1-469-581-21	INDUCTOR, FERRITE BEAD (1005)	
C515	1-125-777-11	CERAMIC CHIP 0.1uF	10% 10V	FB2001	1-400-693-21	INDUCTOR, FERRITE BEAD (1005)	
C516	1-110-569-11	TANTAL. CHIP 47uF	20% 6.3V			< IC >	
C518	1-125-777-11	CERAMIC CHIP 0.1uF	10% 10V	IC101	6-707-481-01	IC D36521A11BLC	
C701	1-164-937-11	CERAMIC CHIP 0.001uF	10% 50V	IC102	6-707-089-01	IC MM3111AWLE	
C702	1-164-943-81	CERAMIC CHIP 0.01uF	10% 16V	IC501	6-708-467-01	IC XC6213B312NR	
C707	1-164-850-11	CERAMIC CHIP 10PF	0.5PF 50V	IC502	6-708-467-01	IC XC6213B312NR	
C708	1-164-850-11	CERAMIC CHIP 10PF	0.5PF 50V	IC503	6-708-472-01	IC XC6215B312NR	
C711	1-125-777-11	CERAMIC CHIP 0.1uF	10% 10V				
C712	1-125-777-11	CERAMIC CHIP 0.1uF	10% 10V				

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
IC504	6-708-440-01	IC XC61CN1202NR		R512	1-218-985-11	RES-CHIP 470K 5%	1/16W
IC506	6-701-734-01	IC XC9105D091MR		R513	1-218-985-11	RES-CHIP 470K 5%	1/16W
IC701	6-712-243-01	IC NAND04GW3B2DN6F		R515	1-218-989-11	RES-CHIP 1M 5%	1/16W
IC702	6-708-473-01	IC XC61CS2DXNR		R516	1-218-989-11	RES-CHIP 1M 5%	1/16W
IC703	6-712-283-01	IC MN101C93KSK		R517	1-218-977-11	RES-CHIP 100K 5%	1/16W
IC2001	6-707-471-01	IC BH31FB1WHFV-TR		R518	1-218-989-11	RES-CHIP 1M 5%	1/16W
IC2002	6-707-089-01	IC MM3111AWLE		R519	1-220-804-11	RES-CHIP 2.2M 5%	1/16W
		< JACK >		R520	1-218-985-11	RES-CHIP 470K 5%	1/16W
J101	1-819-550-23	JACK (⚡) (PLUG IN POWER)		R521	1-218-977-11	RES-CHIP 100K 5%	1/16W
J102	1-819-965-11	JACK (⚡)		R523	1-218-965-11	RES-CHIP 10K 5%	1/16W
		< COIL >		R524	1-218-977-11	RES-CHIP 100K 5%	1/16W
L501	1-419-881-11	COIL, CHOKE 47uH		R525	1-218-985-11	RES-CHIP 470K 5%	1/16W
		< LIQUID CRYSTAL DISPLAY >		R526	1-218-977-11	RES-CHIP 100K 5%	1/16W
LCD701	1-802-628-11	DISPLAY PANEL, LIQUID CRYSTAL		R528	1-218-989-11	RES-CHIP 1M 5%	1/16W
		< TRANSISTOR >		R701	1-218-985-11	RES-CHIP 470K 5%	1/16W
Q101	8-729-044-37	FET 2SK3019TL		R702	1-218-985-11	RES-CHIP 470K 5%	1/16W
Q106	8-729-905-35	TRANSISTOR 2SC4081-R		R703	1-218-965-11	RES-CHIP 10K 5%	1/16W
Q506	6-550-887-01	FET RTF025N03TL		R706	1-208-935-11	METAL CHIP 100K 0.5%	1/16W
Q507	8-729-044-37	FET 2SK3019TL		R707	1-208-935-11	METAL CHIP 100K 0.5%	1/16W
Q508	6-550-747-01	FET 3LP01S-K-TL-E		R709	1-218-965-11	RES-CHIP 10K 5%	1/16W
Q509	6-550-747-01	FET 3LP01S-K-TL-E		R710	1-218-977-11	RES-CHIP 100K 5%	1/16W
Q702	6-550-747-01	FET 3LP01S-K-TL-E		R711	1-218-977-11	RES-CHIP 100K 5%	1/16W
Q703	6-551-761-01	TRANSISTOR UNR31A4G0LS0		R712	1-218-977-11	RES-CHIP 100K 5%	1/16W
Q704	6-550-237-01	TRANSISTOR 2SC5658FS6T2LQ/R		R713	1-218-977-11	RES-CHIP 100K 5%	1/16W
Q2001	6-550-887-01	FET RTF025N03TL		R714	1-218-989-11	RES-CHIP 1M 5%	1/16W
Q2002	8-729-044-37	FET 2SK3019TL		R721	1-218-953-11	RES-CHIP 1K 5%	1/16W
		< RESISTOR >		R722	1-218-990-81	SHORT CHIP 0	
R101	1-218-961-11	RES-CHIP 4.7K 5%	1/16W	R723	1-218-990-81	SHORT CHIP 0	
R102	1-218-990-81	SHORT CHIP 0		R724	1-218-990-81	SHORT CHIP 0	
R104	1-218-941-81	RES-CHIP 100 5%	1/16W	R726	1-218-953-11	RES-CHIP 1K 5%	1/16W
R105	1-218-961-11	RES-CHIP 4.7K 5%	1/16W	R727	1-218-953-11	RES-CHIP 1K 5%	1/16W
R106	1-218-969-11	RES-CHIP 22K 5%	1/16W	R728	1-218-957-11	RES-CHIP 2.2K 5%	1/16W
R107	1-218-973-11	RES-CHIP 47K 5%	1/16W	R733	1-218-985-11	RES-CHIP 470K 5%	1/16W
R108	1-218-953-11	RES-CHIP 1K 5%	1/16W	R734	1-218-965-11	RES-CHIP 10K 5%	1/16W
R109	1-218-949-11	RES-CHIP 470 5%	1/16W	R736	1-218-965-11	RES-CHIP 10K 5%	1/16W
R110	1-218-969-11	RES-CHIP 22K 5%	1/16W	R745	1-218-957-11	RES-CHIP 2.2K 5%	1/16W
R116	1-218-977-11	RES-CHIP 100K 5%	1/16W	R746	1-218-961-11	RES-CHIP 4.7K 5%	1/16W
R118	1-218-969-11	RES-CHIP 22K 5%	1/16W	R747	1-218-965-11	RES-CHIP 10K 5%	1/16W
R119	1-218-973-11	RES-CHIP 47K 5%	1/16W	R748	1-218-969-11	RES-CHIP 22K 5%	1/16W
R120	1-218-965-11	RES-CHIP 10K 5%	1/16W	R749	1-218-957-11	RES-CHIP 2.2K 5%	1/16W
R121	1-218-977-11	RES-CHIP 100K 5%	1/16W	R750	1-218-961-11	RES-CHIP 4.7K 5%	1/16W
R122	1-218-981-11	RES-CHIP 220K 5%	1/16W	R751	1-218-965-11	RES-CHIP 10K 5%	1/16W
R124	1-218-957-11	RES-CHIP 2.2K 5%	1/16W	R752	1-218-969-11	RES-CHIP 22K 5%	1/16W
R126	1-218-969-11	RES-CHIP 22K 5%	1/16W	R753	1-218-977-11	RES-CHIP 100K 5%	1/16W
R128	1-218-949-11	RES-CHIP 470 5%	1/16W	R754	1-218-985-11	RES-CHIP 470K 5%	1/16W
R129	1-218-977-11	RES-CHIP 100K 5%	1/16W	R757	1-218-990-81	SHORT CHIP 0	
R130	1-218-933-11	RES-CHIP 22 5%	1/16W	R2001	1-218-973-11	RES-CHIP 47K 5%	1/16W
R131	1-218-981-11	RES-CHIP 220K 5%	1/16W	R2002	1-218-981-11	RES-CHIP 220K 5%	1/16W
R135	1-218-990-81	SHORT CHIP 0		R2004	1-218-981-11	RES-CHIP 220K 5%	1/16W
R137	1-218-990-81	SHORT CHIP 0		R2010	1-218-957-11	RES-CHIP 2.2K 5%	1/16W
R138	1-218-937-11	RES-CHIP 47 5%	1/16W	R2011	1-218-961-11	RES-CHIP 4.7K 5%	1/16W
R503	1-218-973-11	RES-CHIP 47K 5%	1/16W	R2012	1-218-990-81	SHORT CHIP 0	
R510	1-218-985-11	RES-CHIP 470K 5%	1/16W	R2013	1-218-990-81	SHORT CHIP 0	
R511	1-208-943-11	METAL CHIP 220K 0.5%	1/16W	R2014	1-218-953-11	RES-CHIP 1K 5%	1/16W
				R2015	1-218-990-81	SHORT CHIP 0	
				R2019	1-218-969-11	RES-CHIP 22K 5%	1/16W
				R2020	1-218-977-11	RES-CHIP 100K 5%	1/16W
				R2021	1-218-990-81	SHORT CHIP 0	
				R2023	1-218-977-11	RES-CHIP 100K 5%	1/16W
				R2024	1-218-977-11	RES-CHIP 100K 5%	1/16W

ICD-P620

Ver. 1.1

MAIN **USB**

Ref. No.	Part No.	Description	Remark		
R2025	1-218-989-11	RES-CHIP 1M 5%	1/16W		
		< NETWORK RESISTOR >			
RB101	1-234-378-21	RES, NETWORK 10KX4 (1005)			
		< VARIABLE RESISTOR >			
RV101	1-227-710-21	RES, VAR, CARBON 20K (VOL)			
		< SWITCH >			
S701	1-572-922-11	SWITCH, SLIDE (HOLD)			
S702	1-771-954-21	SWITCH, TACTILE (■)			
S703	1-771-954-21	SWITCH, TACTILE (▶■PLAY/ENTER)			
S704	1-771-954-21	SWITCH, TACTILE (▶▶I+)			
S705	1-771-954-21	SWITCH, TACTILE (-◀◀)			
S706	1-771-954-21	SWITCH, TACTILE (DISPLAY/MENU)			
S707	1-771-954-21	SWITCH, TACTILE (●I■REC)			
S708	1-771-248-11	SWITCH, TACTILE (ERASE)			
S709	1-771-954-21	SWITCH, TACTILE (DIVIDE)			
		< VIBRATOR >			
X701	1-813-724-21	VIBRATOR, CERAMIC (8MHz)			
X702	1-813-652-11	VIBRATOR, CRYSTAL (32.768kHz)			
X2001	1-795-268-21	VIBRATOR, CERAMIC (4.096MHz)			

	A-1486-576-A	USB BOARD, COMPLETE	*****		
		< CAPACITOR >			
C1008	1-164-937-11	CERAMIC CHIP 0.001uF 10%	50V		
		< CONNECTOR >			
CN1001	1-818-513-21	CONNECTOR (SQUARE TYPE) (USB) 5P (USB)			
CN1002	1-819-212-21	CONNECTOR, BOARD TO BOARD 20P			
		< RESISTOR >			
R1003	1-218-937-11	RES-CHIP 47 5%	1/16W		
R1004	1-218-937-11	RES-CHIP 47 5%	1/16W		
R1010	1-216-295-11	SHORT CHIP 0			
R1011	1-216-295-11	SHORT CHIP 0			
R1019	1-218-990-81	SHORT CHIP 0			
R1030	1-218-941-81	RES-CHIP 100 5%	1/16W		
R1031	1-218-941-81	RES-CHIP 100 5%	1/16W		

		MISCELLANEOUS	*****		
MIC101	1-542-758-11	MICROPHONE, ELECTRET CONDENSER (MIC)			
SP101	1-826-927-11	SPEAKER (2.8cm)			

Ref. No.	Part No.	Description	Remark
		ACCESSORIES	*****
1-829-882-12		CORD, CONNECTION (USB)	
2-059-703-02		POUCH, CARRYING (E,KR)	
3-295-268-11		MANUAL, INSTRUCTION (ENGLISH)	(EXCEPT AEP)
3-295-268-21		MANUAL, INSTRUCTION (FRENCH) (CND)	
3-295-268-31		MANUAL, INSTRUCTION (SPANISH) (E)	
3-295-268-41		MANUAL, INSTRUCTION	(TRADITIONAL CHINESE) (E)
3-295-268-61		MANUAL, INSTRUCTION (KOREAN) (E,KR)	
3-295-268-81		MANUAL, INSTRUCTION	(SIMPLIFIED CHINESE) (E)
3-295-276-11		MANUAL (QSG), INSTRUCTION (ENGLISH, FRENCH,SPANISH,DUTCH)	(AEP)
3-295-276-21		MANUAL (QSG), INSTRUCTION (SWEDISH, PORTUGUESE,GERMAN,ITALIAN)	(AEP)
3-295-276-31		MANUAL (QSG), INSTRUCTION (RUSSIAN, POLISH,UKRAINIAN,GREEK)	(AEP)
3-295-276-41		MANUAL (QSG), INSTRUCTION (CZECH, TURKISH,HUNGARIAN)	(AEP)
8-954-047-92		EAR RECEIVER (MDRE0110LPBM)	(E,KR)
X-2190-327-1		SOFT ASSY, APPLICATION (Digital Voice Editor)	(EXCEPT AEP)
X-2190-328-2		SOFT ASSY, APPLICATION (Digital Voice Editor)	(AEP)

MEMO

